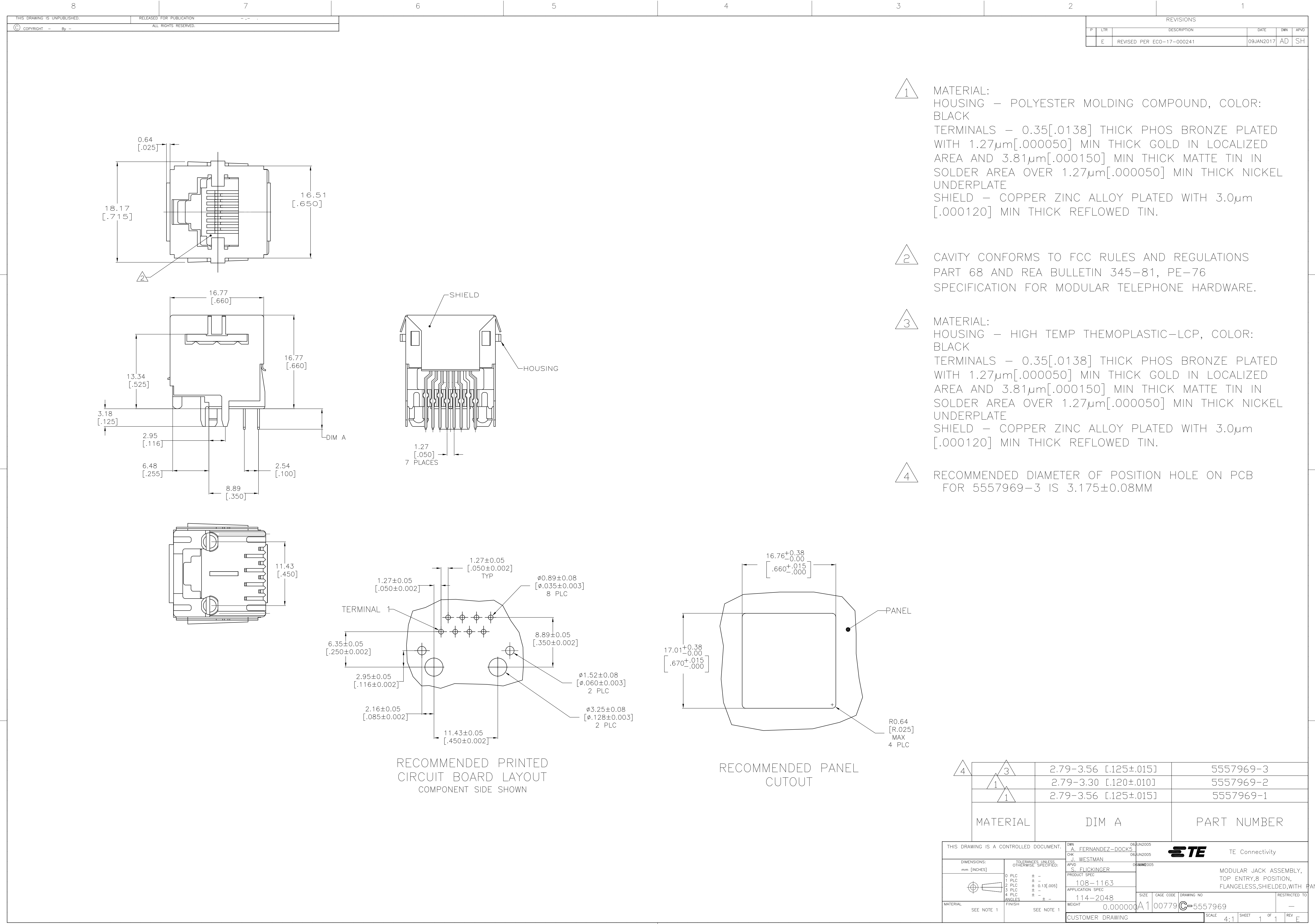


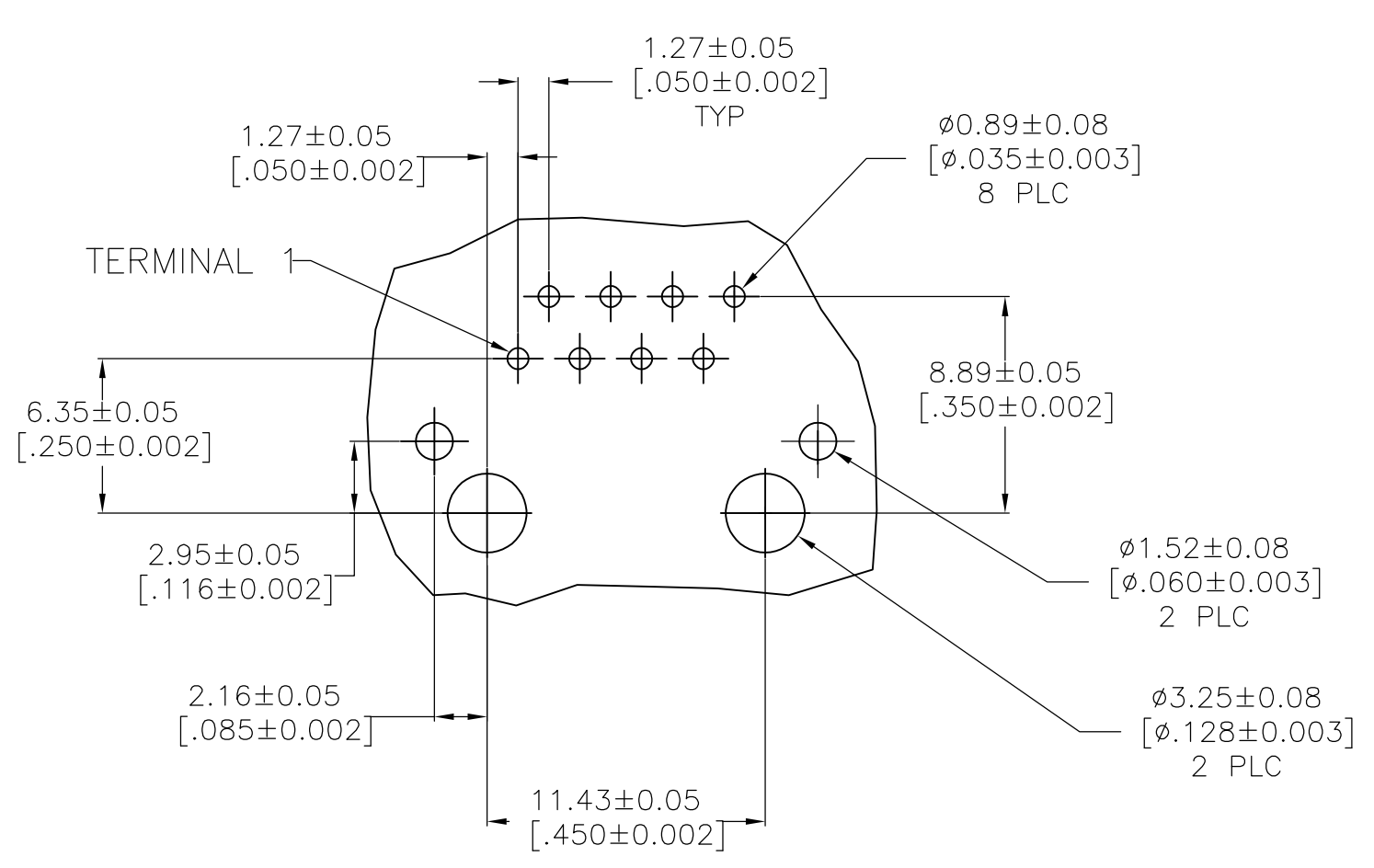


1 MATERIAL:
HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81 μ m[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0 μ m[.000120] MIN THICK REFLOWED TIN.

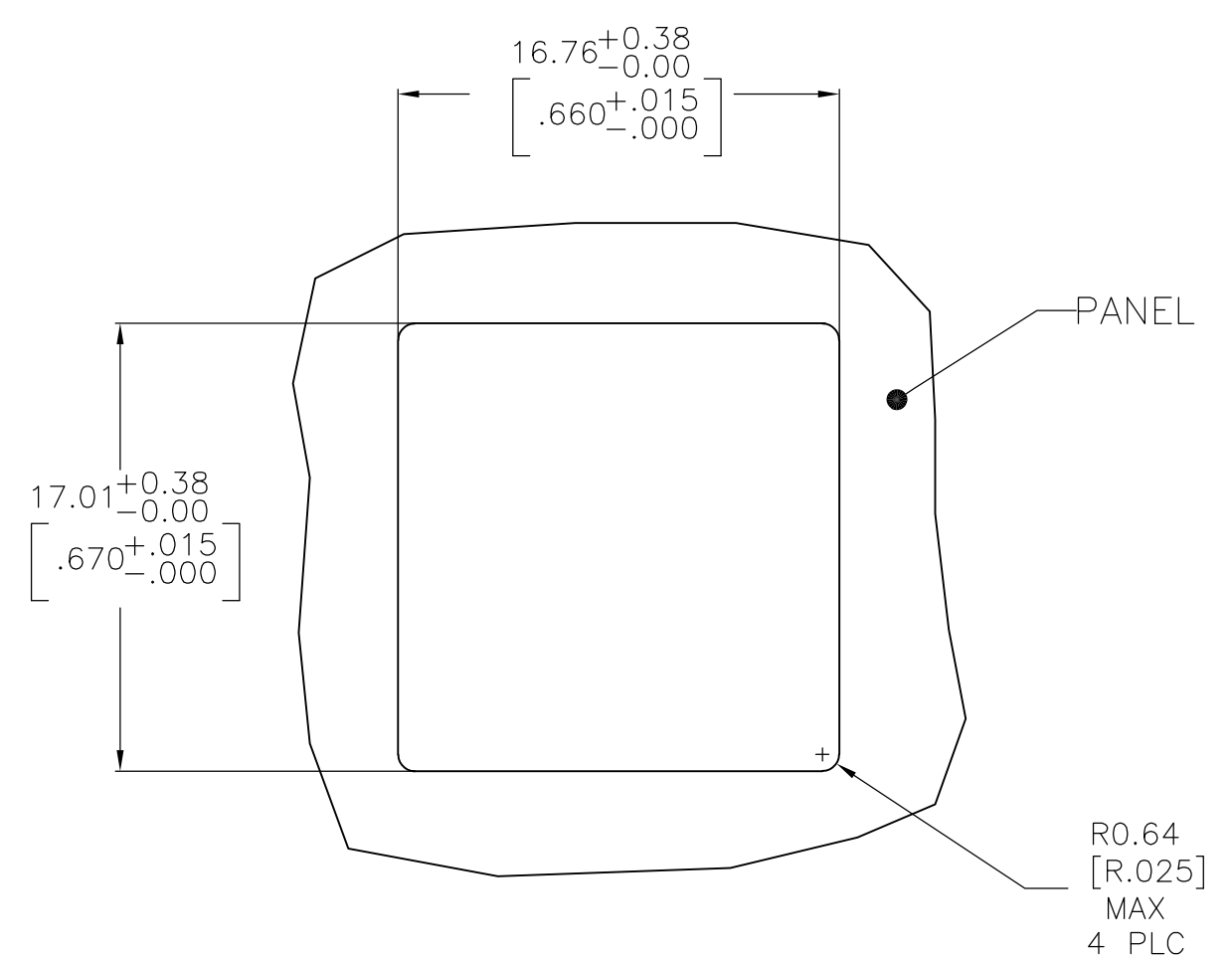
2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345–81, PE–76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

3 MATERIAL:
HOUSING – HIGH TEMP THEMOPLASTIC–LCP, COLOR: BLACK
TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81 μ m[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0 μ m[.000120] MIN THICK REFLOWED TIN.

4 RECOMMENDED DIAMETER OF POSITION HOLE ON PCB FOR 5557969–3 IS 3.175 $\pm$ 0.08MM



RECOMMENDED PRINTED
CIRCUIT BOARD LAYOUT
COMPONENT SIDE SHOWN



RECOMMENDED PANEL
CUTOUT

4 3		2.79-3.56 [.125±.015]	5557969-3
1 1		2.79-3.30 [.120±.010]	5557969-2
1 1		2.79-3.56 [.125±.015]	5557969-1
MATERIAL		DIM A	PART NUMBER
THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN A. FERNANDEZ-DOCKS CHK J. WESTMAN APVD S. FLICKINGER 06JUN2005 06JUN2005 06JUN2005 TE Connectivity	
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH P	
	0 PLC ± - 1 PLC ± - 2 PLC ± 0.13[.005] 3 PLC ± - 4 PLC ± - ANGLES ± -	PRODUCT SPEC 108-1163 APPLICATION SPEC 114-2048	
MATERIAL	FINISH	WEIGHT	RESTRICTED TO
SEE NOTE 1	SEE NOTE 1	0.000000A1	—
CUSTOMER DRAWING		SIZE	SCALE
		CAGE CODE	4:1
		DRAWING NO	SHEET
		00779	1 of 1
		©=5557969	REV E